Advanced FIB Circuit Edit – Front Side Sample Application Training
Abbreviated* Syllabus.

1. Planning front side circuit modification, aspect ratio and distance considerations;
2. Sample preparation, thermal conditioning, charging and drift reduction;
3. Advanced navigation: precision lock, precision beam placement, drift compensation;
4. Basics of GAE theory, advanced GAE techniques;
5. Charge reduction and ESD prevention in electron imaging mode;
6. Circuitry access, via milling, dose estimation;
7. High Aspect Ratio (HAR) via endpoint detection;
8. Conductor and dielectric evaluation, recipe development;
9. Specifics of Cu technology;
10. High Aspect Ratio probe points;

*Detailed syllabus is available upon request sent to: info@partbeamsystech.com

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